

Title (en)  
PROCESS FOR MANUFACTURING A MICROELECTRONIC DEVICE

Title (de)  
VERFAHREN ZUR ERZEUGUNG EINES MIKROELEKTRONISCHEN ELEMENTS

Title (fr)  
PROCEDE DE FABRICATION D'UN DISPOSITIF MICRO-ELECTRONIQUE

Publication  
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Application  
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Priority

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Abstract (en)  
[origin: WO0210858A2] The present invention relates to a process for manufacturing a microelectronic device, comprising providing a substrate with a photoresist image, coating the photoresist image with a shrink material, insolubilizing a portion of the shrink material in contact with the photoresist image, removing a portion of the shrink material which is not insolubilized with a removal solution, further where the removal solution comprises an aqueous solution of a surfactant.

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